

A2

while said wafer is in said first position, spraying a third volume of rinse solution against said wafer and rotating said wafer at a rate such that substantially all of said third volume of rinse solution enters said annular waste inlet.

24. (New) The method of Claim 23 wherein said second volume of rinse solution is smaller than said third volume of rinse solution.

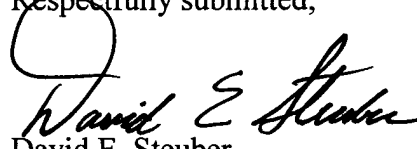
REMARKS

Claims 1-16 have been canceled, and new Claims 17-24 have been added.

EXPRESS MAIL LABEL NO.

EL 710 206 326 US

Respectfully submitted,



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Reg. No. 25,557

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